

SOT2229-1

HLQFP100, plastic, thermal enhanced low profile quad flat package; 100 terminals; 0.5 mm pitch; 14 mm x 14 mm x 1.5 mm body

20 November 2024

Package information



1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFP100
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	12-07-2024
Manufacturer package code	98ASA02131D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	14	-	mm
package width	-	14	-	mm
seated height	-	1.5	1.6	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	100	-	



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2 Package outline

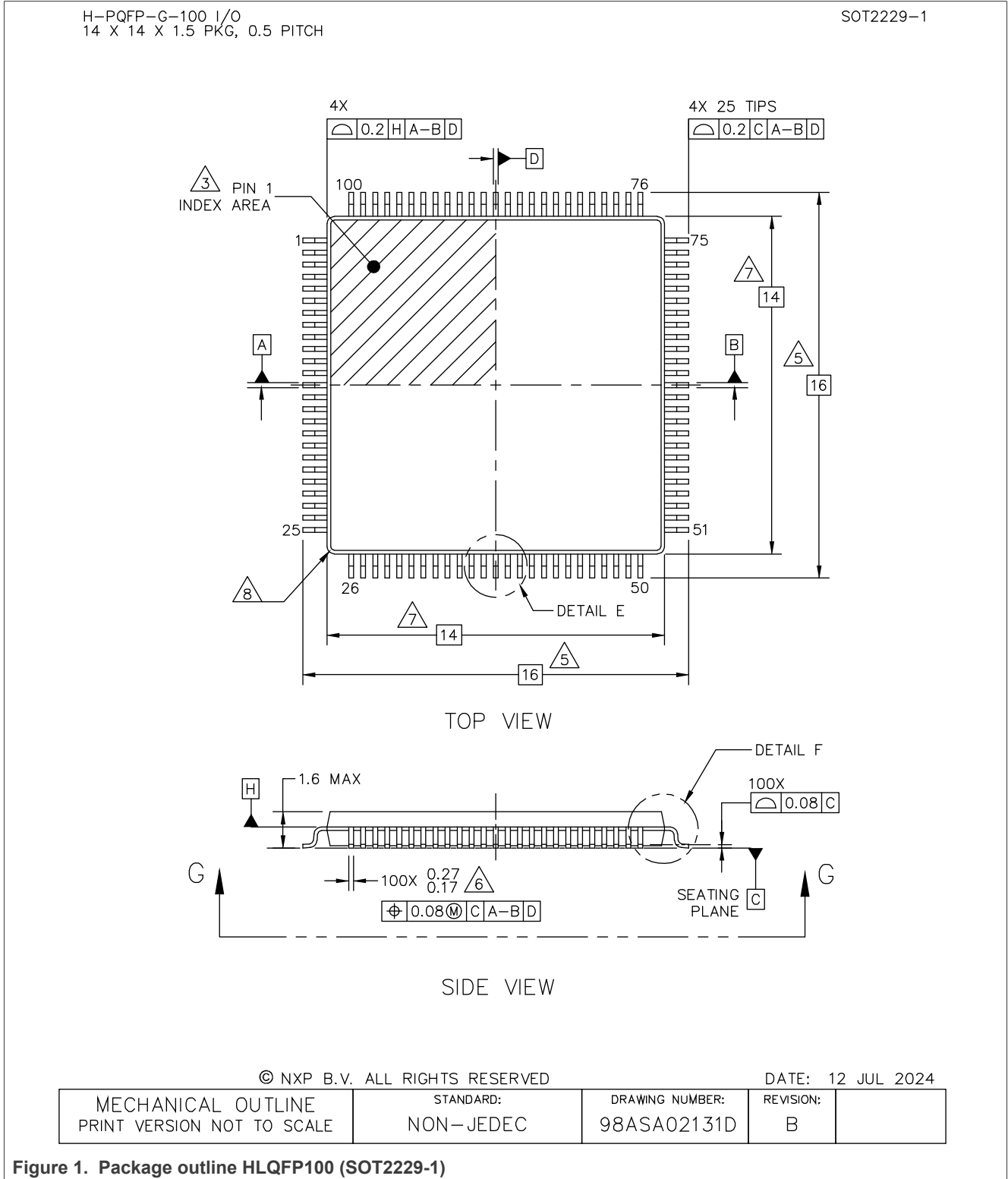
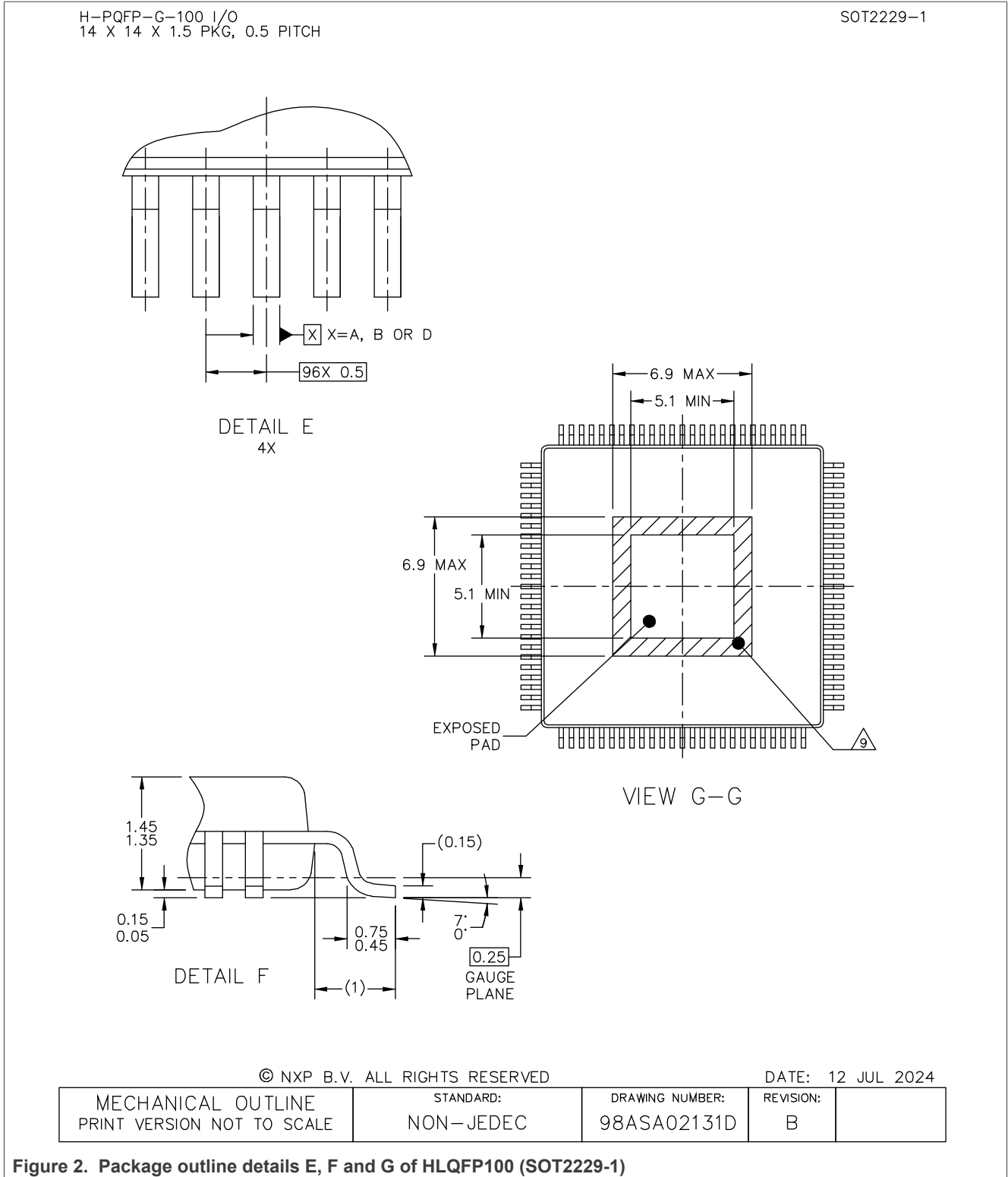


Figure 1. Package outline HLQFP100 (SOT2229-1)

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3 Soldering

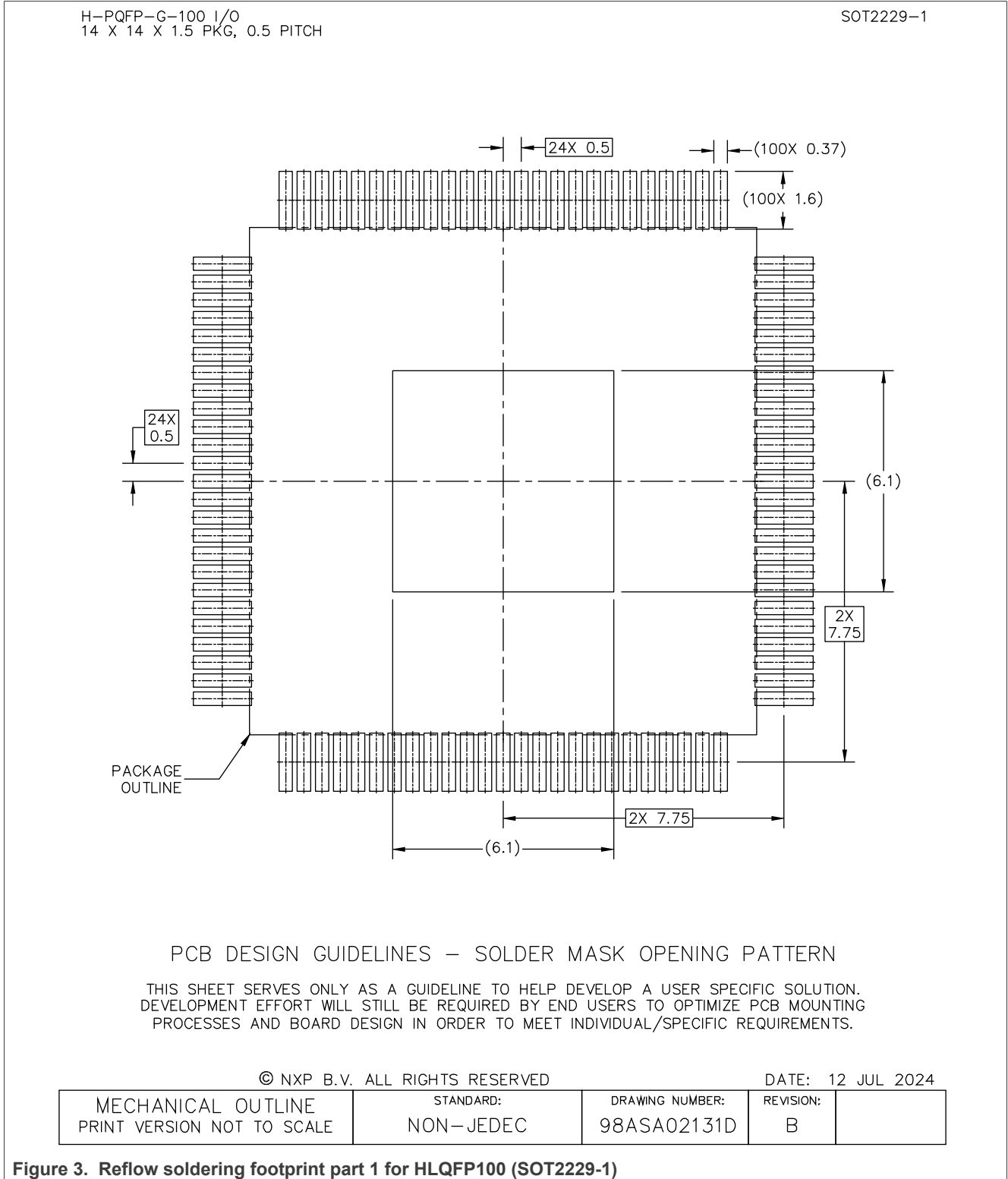
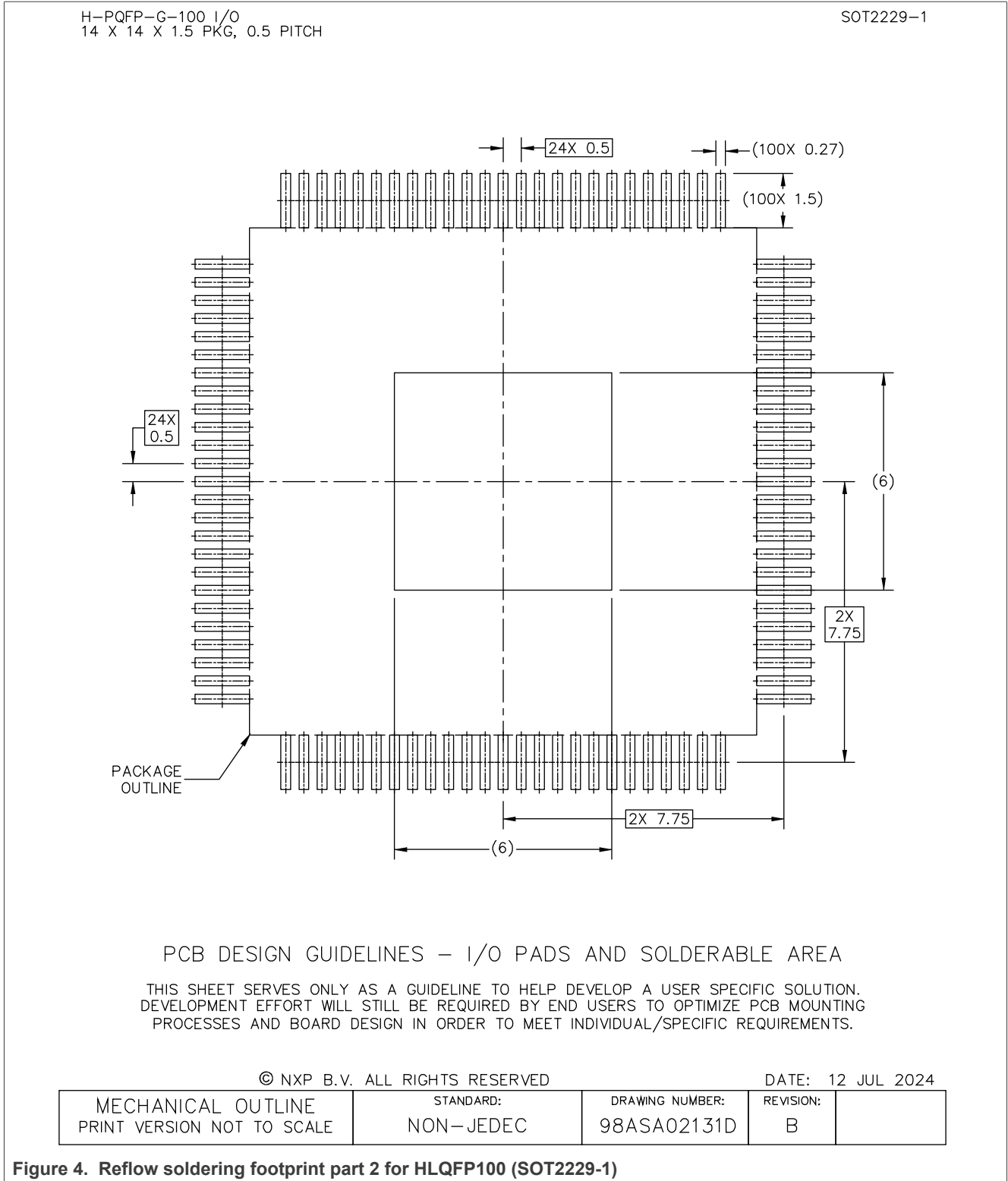
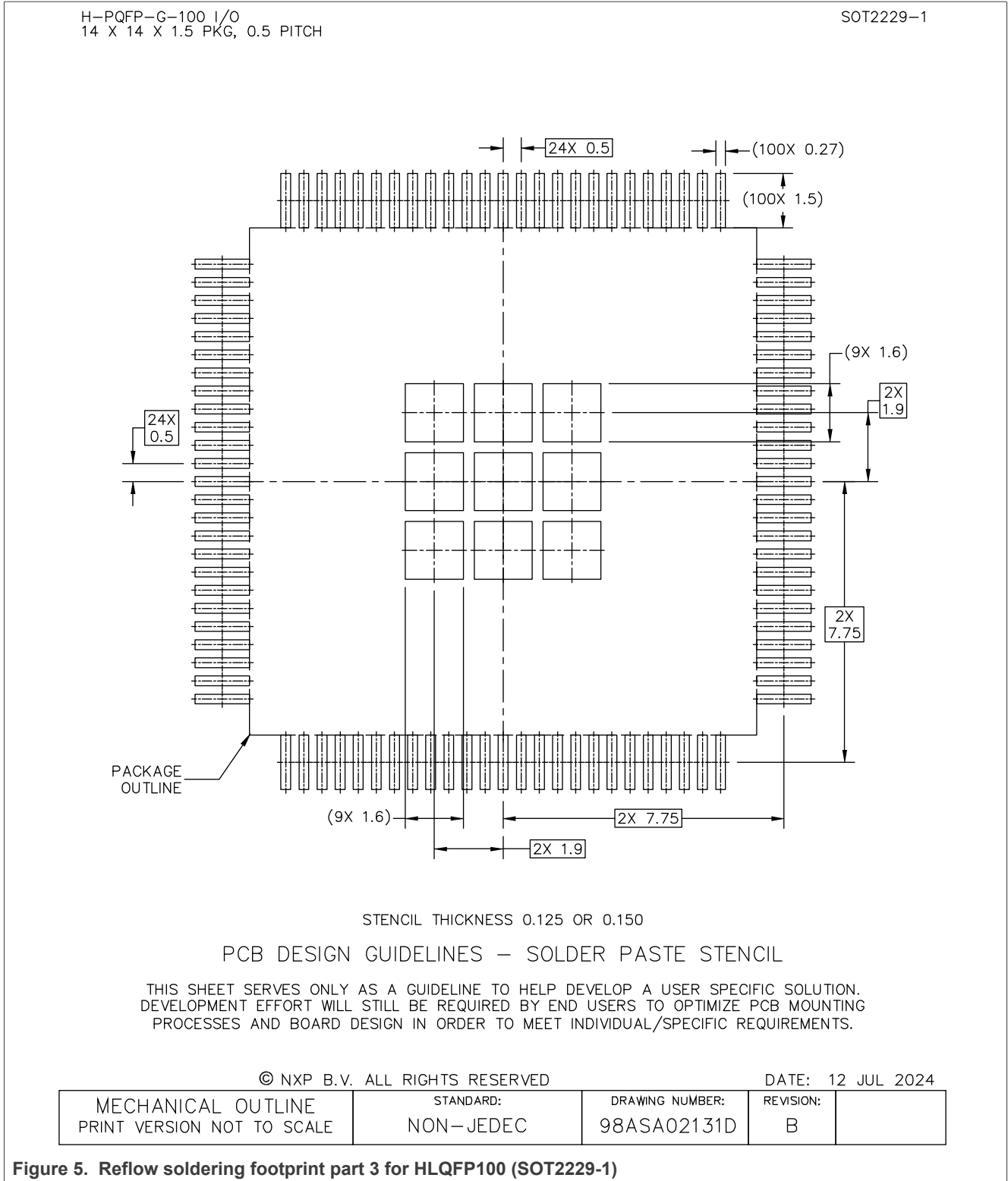


Figure 3. Reflow soldering footprint part 1 for HLQFP100 (SOT2229-1)

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H-PQFP-G-100 I/O
14 X 14 X 1.5 PKG, 0.5 PITCH

SOT2229-1

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
5. DIMENSION TO BE DETERMINED AT SEATING PLANE C.
6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07MM.
7. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
9. HATCHED AREA TO BE KEEP OUT ZONE FOR PCB ROUTING.

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DATE: 12 JUL 2024

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA02131D	REVISION: B	
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Figure 6. Package outline note HLQFP100 (SOT2229-1)

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4 Legal information

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